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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	24MHz
Connectivity	I <sup>2</sup> C, IrDA, LINbus, Microwire, SmartCard, SPI, SSP, UART/USART
Peripherals	Brown-out Detect/Reset, CapSense, LCD, LVD, POR, PWM, WDT
Number of I/O	34
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 5.5V
Data Converters	A/D 8x12b SAR; D/A 2xIDAC
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	40-UFQFN Exposed Pad
Supplier Device Package	40-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c4125lqq-483



### **More Information**

Cypress provides a wealth of data at www.cypress.com to help you to select the right PSoC device for your design, and to help you to quickly and effectively integrate the device into your design. For a comprehensive list of resources, see the knowledge base article KBA86521, How to Design with PSoC 3, PSoC 4, and PSoC 5LP. Following is an abbreviated list for PSoC 4:

- Overview: PSoC Portfolio, PSoC Roadmap
- Product Selectors: PSoC 1, PSoC 3, PSoC 4, PSoC 5LP In addition, PSoC Creator includes a device selection tool.
- Application notes: Cypress offers a large number of PSoC application notes covering a broad range of topics, from basic to advanced level. Recommended application notes for getting started with PSoC 4 are:
  - □ AN79953: Getting Started With PSoC 4
  - □ AN88619: PSoC 4 Hardware Design Considerations
  - □ AN86439: Using PSoC 4 GPIO Pins
  - □ AN57821: Mixed Signal Circuit Board Layout
  - □ AN81623: Digital Design Best Practices
  - □ AN73854: Introduction To Bootloaders
  - □ AN89610: ARM Cortex Code Optimization
  - □ AN90071: CY8CMBRxxx CapSense Design Guide

- Technical Reference Manual (TRM) is in two documents:
  - □ Architecture TRM details each PSoC 4 functional block.
  - □ Registers TRM describes each of the PSoC 4 registers.
- Development Kits:
  - □ CY8CKIT-042, PSoC 4 Pioneer Kit, is an easy-to-use and inexpensive development platform. This kit includes connectors for Arduino™ compatible shields and Digilent® Pmod™ daughter cards.
  - □ CY8CKIT-049 is a very low-cost prototyping platform. It is a low-cost alternative to sampling PSoC 4 devices.
  - CY8CKIT-001 is a common development platform for any one of the PSoC 1, PSoC 3, PSoC 4, or PSoC 5LP families of devices.

The MiniProg3 device provides an interface for flash programming and debug.

### **PSoC Creator**

PSoC Creator is a free Windows-based Integrated Design Environment (IDE). It enables concurrent hardware and firmware design of PSoC 3, PSoC 4, and PSoC 5LP based systems. Create designs using classic, familiar schematic capture supported by over 100 pre-verified, production-ready PSoC Components; see the list of component datasheets. With PSoC Creator, you can:

- 1. Drag and drop component icons to build your hardware system design in the main design workspace
- Codesign your application firmware with the PSoC hardware, using the PSoC Creator IDE C compiler
- 3. Configure components using the configuration tools
- 4. Explore the library of 100+ components
- 5. Review component datasheets

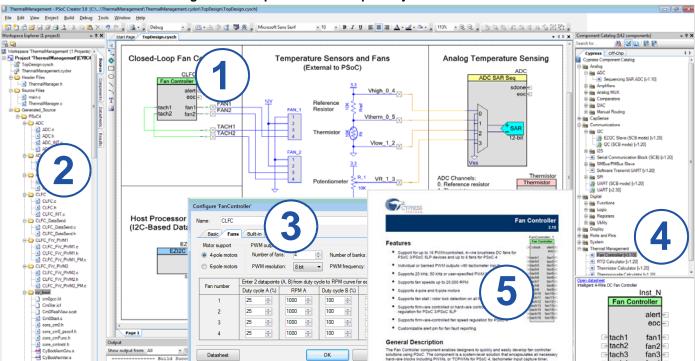


Figure 1. Multiple-Sensor Example Project in PSoC Creator



### **Functional Definition**

### **CPU and Memory Subsystem**

#### **CPU**

The Cortex-M0 CPU in PSoC 4100 is part of the 32-bit MCU subsystem, which is optimized for low power operation with extensive clock gating. It mostly uses 16-bit instructions and executes a subset of the Thumb-2 instruction set. This enables fully compatible binary upward migration of the code to higher performance processors such as the Cortex-M3 and M4, thus enabling upward compatibility. The Cypress implementation includes a hardware multiplier that provides a 32-bit result in one cycle. It includes a nested vectored interrupt controller (NVIC) block with 32 interrupt inputs and also includes a Wakeup Interrupt Controller (WIC), which can wake the processor up from Deep Sleep mode allowing power to be switched off to the main processor when the chip is in Deep Sleep mode. The Cortex-M0 CPU provides a Non-Maskable Interrupt input (NMI). which is made available to the user when it is not in use for system functions requested by the user.

The CPU also includes a debug interface, the serial wire debug (SWD) interface, which is a two-wire form of JTAG; the debug configuration used for PSoC 4100 has four break-point (address) comparators and two watchpoint (data) comparators.

#### Flash

PSoC 4100 has a flash module with a flash accelerator tightly coupled to the CPU to improve average access times from the flash block. The flash block is designed to deliver 0 wait-state (WS) access time at 24 MHz. Part of the flash module can be used to emulate EEPROM operation if required.

The PSoC 4200 Flash supports the following flash protection modes at the memory subsystem level:

- Open: No Protection. Factory default mode in which the product is shipped.
- Protected: User may change from Open to Protected. This mode disables Debug interface accesses. The mode can be set back to Open but only after completely erasing the Flash.
- Kill: User may change from Open to Kill. This mode disables all Debug accesses. The part cannot be erased externally, thus obviating the possibility of partial erasure by power interruption and potential malfunction and security leaks. This is an irrecvocable mode.

In addition, row-level Read/Write protection is also supported to prevent inadvertent Writes as well as selectively block Reads. Flash Read/Write/Erase operations are always available for internal code using system calls.

#### SRAM

SRAM memory is retained during Hibernate.

#### **SROM**

A supervisory ROM that contains boot and configuration routines is provided.

### System Resources

#### Power System

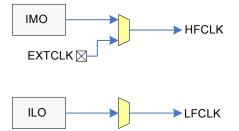
The power system is described in detail in the section Power on page 15. It provides assurance that voltage levels are as required for each respective mode and either delay mode entry (on power-on reset (POR), for example) until voltage levels are as required for proper function or generate resets (brown-out detect (BOD)) or interrupts (low-voltage detect (LVD)). The PSoC 4100 operates with a single external supply over the range of 1.71 V to 5.5 V and has five different power modes, transitions between which are managed by the power system. PSoC 4100 provides Sleep, Deep Sleep, Hibernate, and Stop low-power modes.

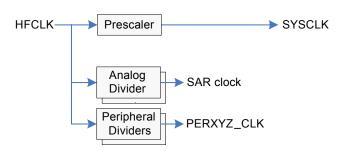
### Clock System

The PSoC 4100 clock system is responsible for providing clocks to all subsystems that require clocks and for switching between different clock sources without glitching. In addition, the clock system ensures that no metastable conditions occur.

The clock system for PSoC 4100 consists of the internal main oscillator (IMO) and the internal low-power oscillator (ILO) and provision for an external clock.

Figure 3. PSoC 4100 MCU Clocking Architecture





The HFCLK signal can be divided down (see PSoC 4100 MCU Clocking Architecture) to generate synchronous clocks for the analog and digital peripherals. There are a total of 12 clock dividers for PSoC 4100, each with 16-bit divide capability. The analog clock leads the digital clocks to allow analog events to occur before digital clock-related noise is generated. The 16-bit capability allows a lot of flexibility in generating fine-grained frequency values and is fully supported in PSoC Creator.



#### IMO Clock Source

The IMO is the primary source of internal clocking in the PSoC 4100. It is trimmed during testing to achieve the specified accuracy. Trim values are stored in nonvolatile latches (NVL). Additional trim settings from flash can be used to compensate for changes. The IMO default frequency is 24 MHz and it can be adjusted between 3 MHz to 24 MHz in steps of 1 MHz. The IMO tolerance with Cypress-provided calibration settings is ±2%.

#### ILO Clock Source

The ILO is a very low power oscillator, which is primarily used to generate clocks for peripheral operation in Deep Sleep mode. ILO-driven counters can be calibrated to the IMO to improve accuracy. Cypress provides a software component, which does the calibration.

#### Watchdog Timer

A watchdog timer is implemented in the clock block running from the ILO; this allows watchdog operation during Deep Sleep and generates a watchdog reset if not serviced before the timeout occurs. The watchdog reset is recorded in the Reset Cause register.

#### Reset

PSoC 4100 can be reset from a variety of sources including a software reset. Reset events are asynchronous and guarantee reversion to a known state. The reset cause is recorded in a register, which is sticky through reset and allows software to determine the cause of the reset. An XRES pin is reserved for external reset to avoid complications with configuration and multiple pin functions during power-on or reconfiguration. The XRES pin has an internal pull-up resistor that is always enabled.

#### Voltage Reference

The PSoC 4100 reference system generates all internally required references. A 1% voltage reference spec is provided for the 12-bit ADC. To allow better signal to noise ratios (SNR) and better absolute accuracy, it is possible to bypass the internal reference using a GPIO pin or to use an external reference for the SAR.

### **Analog Blocks**

#### 12-bit SAR ADC

The 12-bit 806 ksps SAR ADC can operate at a maximum clock rate of 14.5 MHz and requires a minimum of 18 clocks at that frequency to do a 12-bit conversion.

The block functionality is augmented for the user by adding a reference buffer to it (trimmable to  $\pm 1\%$ ) and by providing the choice (for the PSoC 4100 case) of three internal voltage references:  $V_{DD},\,V_{DD}/2,\,$  and  $V_{REF}$  (nominally 1.024 V) as well as an external reference through a GPIO pin. The sample-and-hold (S/H) aperture is programmable allowing the gain bandwidth requirements of the amplifier driving the SAR inputs, which determine its settling time, to be relaxed if required. System performance will be 65 dB for true 12-bit precision providing appropriate references are used and system noise levels permit. To improve performance in noisy conditions, it is possible to provide an external bypass (through a fixed pin location) for the internal reference amplifier.

The SAR is connected to a fixed set of pins through an 8-input sequencer. The sequencer cycles through selected channels autonomously (sequencer scan) and does so with zero switching overhead (that is, aggregate sampling bandwidth is equal to 806 ksps whether it is for a single channel or distributed over several channels). The sequencer switching is effected through a state machine or through firmware driven switching. A feature provided by the sequencer is buffering of each channel to reduce CPU interrupt service requirements. To accommodate signals with varying source impedance and frequency, it is possible to have different sample times programmable for each channel. Also, signal range specification through a pair of range registers (low and high range values) is implemented with a corresponding out-of-range interrupt if the digitized value exceeds the programmed range; this allows fast detection of out-of-range values without the necessity of having to wait for a sequencer scan to be completed and the CPU to read the values and check for out-of-range values in software.

The SAR is able to digitize the output of the on-board temperature sensor for calibration and other temperature-dependent functions. The SAR is not available in Deep Sleep and Hibernate modes as it requires a high-speed clock (up to 18 MHz). The SAR operating range is 1.71 V to 5.5 V.

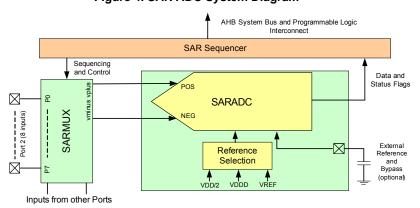


Figure 4. SAR ADC System Diagram



### Two Opamps (CTBm Block)

PSoC 4100 has two opamps with Comparator modes which allow most common analog functions to be performed on-chip eliminating external components; PGAs, voltage buffers, filters, trans-impedance amplifiers, and other functions can be realized with external passives saving power, cost, and space. The on-chip opamps are designed with enough bandwidth to drive the S/H circuit of the ADC without requiring external buffering.

### Temperature Sensor

PSoC 4100 has one on-chip temperature sensor This consists of a diode, which is biased by a current source that can be disabled to save power. The temperature sensor is connected to the ADC, which digitizes the reading and produces a temperature value using Cypress supplied software that includes calibration and linearization.

#### Low-power Comparators

PSoC 4100 has a pair of low-power comparators, which can also operate in the Deep Sleep and Hibernate modes. This allows the analog system blocks to be disabled while retaining the ability to monitor external voltage levels during low-power modes. The comparator outputs are normally synchronized to avoid metastability unless operating in an asynchronous power mode (Hibernate) where the system wake-up circuit is activated by a comparator switch event.

### **Fixed Function Digital**

### Timer/Counter/PWM Block (TCPWM)

The TCPWM block consists of four 16-bit counters with user-programmable period length. There is a Capture register to record the count value at the time of an event (which may be an I/O event), a period register which is used to either stop or auto-reload the counter when its count is equal to the period register, and compare registers to generate compare value signals which are used as PWM duty cycle outputs. The block also provides true and complementary outputs with programmable offset between them to allow use as deadband programmable complementary PWM outputs. It also has a Kill input to force outputs to a predetermined state; for example, this is used in motor drive systems when an overcurrent state is indicated and the PWMs driving the FETs need to be shut off immediately with no time for software intervention.

#### Serial Communication Blocks (SCB)

The PSoC 4100 has two SCBs, which can each implement an  $I^2$ C, UART, or SPI interface.

**I<sup>2</sup>C Mode**: The hardware I<sup>2</sup>C block implements a full multi-master and slave interface (it is capable of multimaster arbitration). This block is capable of operating at speeds of up to 1 Mbps (Fast Mode Plus) and has flexible buffering options to reduce interrupt overhead and latency for the CPU. The FIFO mode is available in all channels and is very useful in the absence of DMA.

The I<sup>2</sup>C peripheral is compatible with the I<sup>2</sup>C Standard-mode, Fast-mode, and Fast-Mode Plus devices as defined in the NXP I<sup>2</sup>C-bus specification and user manual (UM10204). The I<sup>2</sup>C bus I/O is implemented with GPIO in open-drain modes. The I<sup>2</sup>C bus uses open-drain drivers for clock and data with pull-up resistors on the bus for clock and data connected to all nodes. The required Rise and Fall times for different I<sup>2</sup>C speeds are guaranteed by using appropriate pull-up resistor values depending on VDD, Bus Capacitance, and resistor tolerance. For detailed information on how to calculate the optimum pull-up resistor value for your design, refer to the UM10204 I2C bus specification and user manual (the latest revision is available at www.nxp.com).

PSoC 4100 is not completely compliant with the I<sup>2</sup>C spec in the following respects:

- GPIO cells are not overvoltage-tolerant and, therefore, cannot be hot-swapped or powered up independently of the rest of the I<sup>2</sup>C system.
- Fast-mode Plus has an I<sub>OL</sub> specification of 20 mA at a V<sub>OL</sub> of 0.4 V. The GPIO cells can sink a maximum of 8-mA I<sub>OL</sub> with a V<sub>OL</sub> maximum of 0.6 V.
- Fast-mode and Fast-mode Plus specify minimum Fall times, which are not met with the GPIO cell; Slow strong mode can help meet this spec depending on the Bus Load.
- When the SCB is an I<sup>2</sup>C master, it interposes an IDLE state between NACK and Repeated Start; the I<sup>2</sup>C spec defines Bus free as following a Stop condition so other Active Masters do not intervene but a Master that has just become activated may start an Arbitration cycle.
- When the SCB is in I<sup>2</sup>C slave mode, and Address Match on External Clock is enabled (EC\_AM = 1) along with operation in the internally clocked mode (EC\_OP = 0), then its I<sup>2</sup>C address must be even.

**UART Mode**: This is a full-feature UART operating at up to 1 Mbps. It supports automotive single-wire interface (LIN), infrared interface (IrDA), and SmartCard (ISO7816) protocols, all of which are minor variants of the basic UART protocol. In addition, it supports the 9-bit multiprocessor mode that allows addressing of peripherals connected over common RX and TX lines. Common UART functions such as parity error, break detect, and frame error are supported. An 8-deep FIFO allows much greater CPU service latencies to be tolerated.

**SPI Mode**: The SPI mode supports full Motorola SPI, TI SSP (essentially adds a start pulse used to synchronize SPI Codecs), and National Microwire (half-duplex form of SPI). The SPI block can use the FIFO.



# **Pinouts**

The following is the pin-list for PSoC 4100 (44-TQFP, 40-QFN, 28-SSOP, and 48-TQFP). Port 2 comprises of the high-speed Analog inputs for the SAR Mux. P1.7 is the optional external input and bypass for the SAR reference. Ports 3 and 4 contain the Digital Communication channels. All pins support CSD CapSense and analog mux bus connections.

44	4-TQFP	40	-QFN	28	3-SSOP	48	3-TQFP		Alte	ernate Functions f	or Pins		Dia Description
Pin	Name	Pin	Name	Pin	Name	Pin	Name	Analog	Alt 1	Alt 2	Alt 3	Alt 4	- Pin Description
1	VSS	-	-	-	-	-	-	-	_	-	-	_	Ground
2	P2.0	1	P2.0	-	-	2	P2.0	sarmux.0	-	-	-	_	Port 2 Pin 0: gpio, lcd, csd, sarmux
3	P2.1	2	P2.1	-	-	3	P2.1	sarmux.1	-	-	-	_	Port 2 Pin 1: gpio, lcd, csd, sarmux
4	P2.2	3	P2.2	5	P2.2	4	P2.2	sarmux.2	-	-	-	_	Port 2 Pin 2: gpio, lcd, csd, sarmux
5	P2.3	4	P2.3	6	P2.3	5	P2.3	sarmux.3	-	-	-	ı	Port 2 Pin 3: gpio, lcd, csd, sarmux
6	P2.4	5	P2.4	7	P2.4	6	P2.4	sarmux.4	tcpwm0_p[1]	_	_	_	Port 2 Pin 4: gpio, lcd, csd, sarmux, pwm
7	P2.5	6	P2.5	8	P2.5	7	P2.5	sarmux.5	tcpwm0_n[1]	-	-	_	Port 2 Pin 5: gpio, lcd, csd, sarmux, pwm
8	P2.6	7	P2.6	9	P2.6	8	P2.6	sarmux.6	tcpwm1_p[1]	-	-	ı	Port 2 Pin 6: gpio, lcd, csd, sarmux, pwm
9	P2.7	8	P2.7	10	P2.7	9	P2.7	sarmux.7	tcpwm1_n[1]	-	-	_	Port 2 Pin 7: gpio, lcd, csd, sarmux, pwm
10	VSS	9	VSS	-	-	-	-	-	-	-	-	_	Ground
-	-	1	-	-	-	10	NC	-	-	-	-	-	No Connect
-	_	-	-	-	-	11	NC	-	-	-	-	_	No Connect
11	P3.0	10	P3.0	11	P3.0	12	P3.0	-	tcpwm0_p[0]	scb1_uart_rx[0]	scb1_i2c_scl[0]	scb1_spi_mosi[0]	Port 3 Pin 0: gpio, lcd, csd, pwm, scb1
12	P3.1	11	P3.1	12	P3.1	13	P3.1	-	tcpwm0_n[0]	scb1_uart_tx[0]	scb1_i2c_sda[0]	scb1_spi_miso[0]	Port 3 Pin 1: gpio, lcd, csd, pwm, scb1
13	P3.2	12	P3.2	13	P3.2	14	P3.2	-	tcpwm1_p[0]	_	swd_io[0]	scb1_spi_clk[0]	Port 3 Pin 2: gpio, lcd, csd, pwm, scb1, swd
-	_	-	-	-	-	15	VSSD	-	-	-	-	_	Ground
14	P3.3	13	P3.3	14	P3.3	16	P3.3	-	tcpwm1_n[0]	_	swd_clk[0]	scb1_spi_ssel_0[0]	Port 3 Pin 3: gpio, lcd, csd, pwm, scb1, swd
15	P3.4	14	P3.4	-	-	17	P3.4	-	tcpwm2_p[0]	-	-	scb1_spi_ssel_1	Port 3 Pin 4: gpio, lcd, csd, pwm, scb1
16	P3.5	15	P3.5	-	-	18	P3.5	-	tcpwm2_n[0]	-	-	scb1_spi_ssel_2	Port 3 Pin 5: gpio, lcd, csd, pwm, scb1
17	P3.6	16	P3.6	-	-	19	P3.6	-	tcpwm3_p[0]	_	swd_io[1]	scb1_spi_ssel_3	Port 3 Pin 6: gpio, lcd, csd, pwm, scb1, swd
18	P3.7	17	P3.7	-	-	20	P3.7	-	tcpwm3_n[0]	-	swd_clk[1]	_	Port 3 Pin 7: gpio, lcd, csd, pwm, swd
19	VDDD	-	-	-	-	21	VDDD	-	-	-	-	_	Digital Supply, 1.8 - 5.5V
20	P4.0	18	P4.0	15	P4.0	22	P4.0	-	-	scb0_uart_rx	scb0_i2c_scl	scb0_spi_mosi	Port 4 Pin 0: gpio, lcd, csd, scb0
21	P4.1	19	P4.1	16	P4.1	23	P4.1	-	-	scb0_uart_tx	scb0_i2c_sda	scb0_spi_miso	Port 4 Pin 1: gpio, lcd, csd, scb0
22	P4.2	20	P4.2	17	P4.2	24	P4.2	csd_c_mod	_	-	-	scb0_spi_clk	Port 4 Pin 2: gpio, lcd, csd, scb0
23	P4.3	21	P4.3	18	P4.3	25	P4.3	csd_c_sh_tank	-	-	-	scb0_spi_ssel_0	Port 4 Pin 3: gpio, lcd, csd, scb0
_	_	_	-	_	-	26	NC	_	-	-	-	-	No Connect
_		_	-	_	-	27	NC	_	-	-	-	-	No Connect

Document Number: 001-87220 Rev. \*H



35-	Ball CSP		Alte	rnate Functions	for Pins	Pin Description	
Pin	Name	Analog	Alt 1	Alt 2	Alt 3	Alt 4	r iii Description
C6	P1.2	ctb.oa0.out	tcpwm3_p[1]	_	_	_	Port 1 Pin 2: gpio, lcd, csd, ctb, pwm
D7	P1.3	ctb.oa1.out	tcpwm3_n[1]	_	-	-	Port 1 Pin 3: gpio, lcd, csd, ctb, pwm
D4	P1.4	ctb.oa1.inm	_	_	_	_	Port 1 Pin 4: gpio, lcd, csd, ctb
D5	P1.5	ctb.oa1.inp	_	_	_	_	Port 1 Pin 5: gpio, lcd, csd, ctb
D6	P1.6	ctb.oa0.inp_alt	_	_	_	_	Port 1 Pin 6: gpio, lcd, csd
E7	P1.7/VREF	ctb.oa1.inp_alt ext_vref	-	-	-	-	Port 1 Pin 7: gpio, lcd, csd, ext_ref

### Descriptions of the Pin functions are as follows:

**VDDD**: Power supply for both analog and digital sections (where there is no  $V_{DDA}$  pin).

**VDDA**: Analog V<sub>DD</sub> pin where package pins allow; shorted to V<sub>DDD</sub> otherwise.

VSSA: Analog ground pin where package pins allow; shorted to VSS otherwise

VSS: Ground pin.

VCCD: Regulated Digital supply (1.8 V ±5%).

Port Pins can all be used as LCD Commons, LCD Segment drivers, or CSD sense and shield pins can be connected to AMUXBUS A or B or can all be used as GPIO pins that can be driven by firmware or DSI signals.

The following packages are supported: 48-pin TQFP, 44-pin TQFP, 40-pin QFN, and 28-pin SSOP.

Document Number: 001-87220 Rev. \*H



# **Development Support**

The PSoC 4100 family has a rich set of documentation, development tools, and online resources to assist you during your development process. Visit <a href="https://www.cypress.com/go/psoc4">www.cypress.com/go/psoc4</a> to find out more.

#### **Documentation**

A suite of documentation supports the PSoC 4100 family to ensure that you can find answers to your questions quickly. This section contains a list of some of the key documents.

**Software User Guide**: A step-by-step guide for using PSoC Creator. The software user guide shows you how the PSoC Creator build process works in detail, how to use source control with PSoC Creator, and much more.

**Component Datasheets**: The flexibility of PSoC allows the creation of new peripherals (components) long after the device has gone into production. Component data sheets provide all of the information needed to select and use a particular component, including a functional description, API documentation, example code, and AC/DC specifications.

**Application Notes**: PSoC application notes discuss a particular application of PSoC in depth; examples include brushless DC motor control and on-chip filtering. Application notes often include example projects in addition to the application note document.

**Technical Reference Manual**: The Technical Reference Manual (TRM) contains all the technical detail you need to use a PSoC device, including a complete description of all PSoC registers. The TRM is available in the Documentation section at www.cypress.com/psoc4.

#### Online

In addition to print documentation, the Cypress PSoC forums connect you with fellow PSoC users and experts in PSoC from around the world, 24 hours a day, 7 days a week.

### **Tools**

With industry standard cores, programming, and debugging interfaces, the PSoC 4100 family is part of a development tool ecosystem. Visit us at <a href="https://www.cypress.com/go/psoccreator">www.cypress.com/go/psoccreator</a> for the latest information on the revolutionary, easy to use PSoC Creator IDE, supported third party compilers, programmers, debuggers, and development kits.



# **Analog Peripherals**

Opamp

**Table 8. Opamp Specifications (Guaranteed by Characterization)** 

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
	I <sub>DD</sub>	Opamp block current. No load.	_	-	-	_	
SID269	I <sub>DD_HI</sub>	Power = high	_	1100	1850	μΑ	
SID270	I <sub>DD_MED</sub>	Power = medium	_	550	950	μA	
SID271	I <sub>DD_LOW</sub>	Power = low	_	150	350	μA	
	GBW	Load = 20 pF, 0.1 mA. V <sub>DDA</sub> = 2.7 V	_	_	_	_	
SID272	GBW_HI	Power = high	6	_	_	MHz	
SID273	GBW_MED	Power = medium	4	_	_	MHz	
SID274	GBW_LO	Power = low	_	1	_	MHz	
	I <sub>OUT_MAX</sub>	V <sub>DDA</sub> ≥ 2.7 V, 500 mV from rail	_	_	_	_	
SID275	I <sub>OUT_MAX_HI</sub>	Power = high	10	_	_	mA	
SID276	I <sub>OUT_MAX_MID</sub>	Power = medium	10	_	_	mA	
SID277	I <sub>OUT_MAX_LO</sub>	Power = low	_	5	_	mA	
	I <sub>OUT</sub>	V <sub>DDA</sub> = 1.71 V, 500 mV from rail	_	_	_	_	
SID278	I <sub>OUT_MAX_HI</sub>	Power = high	4	_	_	mA	
SID279	I <sub>OUT MAX MID</sub>	Power = medium	4	_	_	mA	
SID280	I <sub>OUT_MAX_LO</sub>	Power = low	_	2	_	mA	
SID281	V <sub>IN</sub>	Charge pump on, V <sub>DDA</sub> ≥ 2.7 V	-0.05	_	V <sub>DDA</sub> – 0.2	V	
SID282	V <sub>CM</sub>	Charge pump on, V <sub>DDA</sub> ≥ 2.7 V	-0.05	_	$V_{DDA} - 0.2$	V	
	V <sub>OUT</sub>	$V_{DDA} \ge 2.7 \text{ V}$	_	_	_		
SID283	V <sub>OUT_1</sub>	Power = high, Iload=10 mA	0.5	_	V <sub>DDA</sub> – 0.5	V	
SID284	V <sub>OUT_2</sub>	Power = high, Iload=1 mA	0.2	_	V <sub>DDA</sub> – 0.2	V	
SID285	V <sub>OUT_3</sub>	Power = medium, Iload=1 mA	0.2	_	$V_{DDA} - 0.2$	V	
SID286	V <sub>OUT_4</sub>	Power = low, Iload=0.1 mA	0.2	_	V <sub>DDA</sub> – 0.2	V	
SID288	V <sub>OS_TR</sub>	Offset voltage, trimmed	1	±0.5	1	mV	High mode
SID288A	V <sub>OS_TR</sub>	Offset voltage, trimmed	_	±1	_	mV	Medium mode
SID288B	V <sub>OS_TR</sub>	Offset voltage, trimmed	_	±2	_	mV	Low mode
SID290	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	-10	±3	10	μV/°C	High mode. T <sub>A</sub> ≤ 85 °C
SID290Q	VOS_DR_TR	Offset voltage drift, trimmed	15	±3	15	μV/°C	High mode. $T_A \le 105 ^{\circ}\text{C}$
SID290A	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	_	±10	-	μV/°C	Medium mode
SID290B	V <sub>OS_DR_TR</sub>	Offset voltage drift, trimmed	_	±10	-	μV/°C	Low mode
SID291	CMRR	DC	70	80	_	dB	V <sub>DDD</sub> = 3.6 V
SID292	PSRR	At 1 kHz, 100-mV ripple	70	85	_	dB	V <sub>DDD</sub> = 3.6 V
	Noise		_	_	_	_	
SID293	V <sub>N1</sub>	Input referred, 1 Hz - 1GHz, power = high	_	94	_	μVrms	
SID294	V <sub>N2</sub>	Input referred, 1 kHz, power = high	_	72	_	nV/rtHz	
SID295	V <sub>N3</sub>	Input referred, 10kHz, power = high	_	28	_	nV/rtHz	
SID296	V <sub>N4</sub>	Input referred, 100kHz, power = high	_	15	_	nV/rtHz	

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Table 8. Opamp Specifications (Guaranteed by Characterization) (continued)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID297	Cload	Stable up to maximum load. Performance specs at 50 pF.	-	ı	125	pF	
SID298	Slew_rate	Cload = 50 pF, Power = High, V <sub>DDA</sub> ≥ 2.7 V	6	-	_	V/µs	
SID299	T_op_wake	From disable to enable, no external RC dominating	_	300	_	μs	
SID299A	OL_GAIN	Open Loop Gain	_	90	_	dB	Guaranteed by design
	Comp_mode	Comparator mode; 50-mV drive, Trise = Tfall (approx)	_	-	_		
SID300	T <sub>PD1</sub>	Response time; power = high	_	150	_	ns	
SID301	T <sub>PD2</sub>	Response time; power = medium	_	400	_	ns	
SID302	T <sub>PD3</sub>	Response time; power = low	_	2000	_	ns	
SID303	Vhyst_op	Hysteresis	-	10	ı	mV	

# Comparator

Table 9. Comparator DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID85	V <sub>OFFSET2</sub>	Input offset voltage, Common Mode voltage range from 0 to V <sub>DD</sub> -1	-	_	±4	mV	
SID85A	V <sub>OFFSET3</sub>	Input offset voltage. Ultra low-power mode ( $V_{DDD} \ge 2.2 \text{ V for Temp} < 0 ^{\circ}\text{C}$ , $V_{DDD} \ge 1.8 \text{ V for Temp} > 0 ^{\circ}\text{C}$ )	_	±12	_	mV	
SID86	V <sub>HYST</sub>	Hysteresis when enabled, Common Mode voltage range from 0 to V <sub>DD</sub> -1.	_	10	35	mV	Guaranteed by characterization
SID87	V <sub>ICM1</sub>	Input common mode voltage in normal mode	0	_	V <sub>DDD</sub> – 0.1	V	Modes 1 and 2.
SID247	V <sub>ICM2</sub>	Input common mode voltage in low power mode (V <sub>DDD</sub> ≥ 2.2 V for Temp < 0 °C, V <sub>DDD</sub> ≥ 1.8 V for Temp > 0 °C)	0	_	V <sub>DDD</sub>	V	
SID247A	V <sub>ICM3</sub>	Input common mode voltage in ultra low power mode	0	_	V <sub>DDD</sub> – 1.15	V	
SID88	CMRR	Common mode rejection ratio	50	_	_	dB	V <sub>DDD</sub> ≥ 2.7 V. Guaranteed by characterization
SID88A	CMRR	Common mode rejection ratio	42	_	_	dB	V <sub>DDD</sub> < 2.7 V. Guaranteed by characterization
SID89	I <sub>CMP1</sub>	Block current, normal mode	-	_	400	μΑ	Guaranteed by characterization
SID248	I <sub>CMP2</sub>	Block current, low power mode	_	_	100	μΑ	Guaranteed by characterization
SID259	I <sub>CMP3</sub>	Block current, ultra low power mode $(V_{DDD} \ge 2.2 \text{ V for Temp} < 0 \text{ °C}, V_{DDD} \ge 1.8 \text{ V for Temp} > 0 \text{ °C})$	-	6	28	μA	Guaranteed by characterization
SID90	Z <sub>CMP</sub>	DC input impedance of comparator	35	_	_	ΜΩ	Guaranteed by characterization

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# Table 10. Comparator AC Specifications

(Guaranteed by Characterization)

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID91	T <sub>RESP1</sub>	Response time, normal mode	-	-	110	ns	50-mV overdrive
SID258	T <sub>RESP2</sub>	Response time, low power mode	1	-	200	ns	50-mV overdrive
SID92	T <sub>RESP3</sub>	Response time, ultra low power mode $(V_{DDD} \ge 2.2 \text{ V for Temp} < 0 ^{\circ}\text{C}, V_{DDD} \ge 1.8 \text{ V for Temp} > 0 ^{\circ}\text{C})$	_	_	15	μs	200-mV overdrive

# Temperature Sensor

# **Table 11. Temperature Sensor Specifications**

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID93	T <sub>SENSACC</sub>	Temperature sensor accuracy	<b>-</b> 5	±1	+5	°C	–40 to +85 °C

# SAR ADC

# Table 12. SAR ADC DC Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID94	A_RES	Resolution	_	-	12	bits	
SID95	A_CHNIS_S	Number of channels - single ended	_	-	8		8 full speed
SID96	A-CHNKS_D	Number of channels - differential	-	-	4		Diff inputs use neighboring I/O
SID97	A-MONO	Monotonicity	_	-	_		Yes. Based on characterization
SID98	A_GAINERR	Gain error	-	_	±0.1	%	With external reference. Guaranteed by characterization
SID99	A_OFFSET	Input offset voltage	_	ı	2	mV	Measured with 1-V V <sub>REF.</sub> Guaranteed by characterization
SID100	A_ISAR	Current consumption	_	_	1	mA	
SID101	A_VINS	Input voltage range - single ended	V <sub>SS</sub>	_	$V_{DDA}$	V	Based on device characterization
SID102	A_VIND	Input voltage range - differential	V <sub>SS</sub>	-	$V_{DDA}$	V	Based on device characterization
SID103	A_INRES	Input resistance	-	_	2.2	ΚΩ	Based on device characterization
SID104	A_INCAP	Input capacitance	_	-	10	pF	Based on device characterization
SID106	A_PSRR	Power supply rejection ratio	70	-	-	dB	
SID107	A_CMRR	Common mode rejection ratio	66	_	_	dB	Measured at 1 V
SID111	A_INL	Integral non linearity	-1.7	_	+2	LSB	V <sub>DD</sub> = 1.71 to 5.5, 806 ksps, V <sub>REF</sub> = 1 to 5.5.
SID111A	A_INL	Integral non linearity	-1.5	_	+1.7	LSB	V <sub>DDD</sub> = 1.71 to 3.6, 806 ksps, V <sub>REF</sub> = 1.71 to V <sub>DDD</sub> .

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CSD

Table 14. CSD Specifications

Spec ID#	Parameter	Description	Min	Тур	Max	Units	Details/ Conditions
SID.CSD#16	IDAC1IDD	IDAC1 (8 bits) block current	-	_	1125	μA	
SID.CSD#17	IDAC2IDD	IDAC2 (7 bits) block current	-	_	1125	μA	
SID308	VCSD	Voltage range of operation	1.71	_	5.5	V	
SID308A	VCOMPIDAC	Voltage compliance range of IDAC for S0	0.8	_	V <sub>DD</sub> -0.8	V	
SID309	IDAC1	DNL for 8-bit resolution	<b>-1</b>	_	1	LSB	
SID310	IDAC1	INL for 8-bit resolution	-3	_	3	LSB	
SID311	IDAC2	DNL for 7-bit resolution	-1	_	1	LSB	
SID312	IDAC2	INL for 7-bit resolution	-3	_	3	LSB	
SID313	SNR	Ratio of counts of finger to noise, 0.1-pF sensitivity	5	_	_	Ratio	Capacitance range of 9 to 35 pF, 0.1-pF sensitivity
SID314	IDAC1_CRT1	Output current of IDAC1 (8 bits) in High range	-	612	_	uA	
SID314A	IDAC1_CRT2	Output current of IDAC1 (8 bits) in Low range	_	306	-	uA	
SID315	IDAC2_CRT1	Output current of IDAC2 (7 bits) in High range	_	304.8	-	uA	
SID315A	IDAC2_CRT2	Output current of IDAC2 (7 bits) in Low range	_	152.4	-	uA	
SID320	IDACOFFSET	All zeroes input	_	_	±1	LSB	
SID321	IDACGAIN	Full-scale error less offset	_	_	±10	%	
SID322	IDACMISMATCH	Mismatch between IDACs	_	_	7	LSB	
SID323	IDACSET8	Settling time to 0.5 LSB for 8-bit IDAC	-	_	10	μs	Full-scale transition. No external load.
SID324	IDACSET7	Settling time to 0.5 LSB for 7-bit IDAC	-	-	10	μs	Full-scale transition. No external load.
SID325	CMOD	External modulator capacitor	-	2.2	_	nF	5-V rating, X7R or NP0 cap.

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# Voltage Monitors

Table 30. Voltage Monitors DC Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID195	V <sub>LVI1</sub>	LVI_A/D_SEL[3:0] = 0000b	1.71	1.75	1.79	V	
SID196	V <sub>LVI2</sub>	LVI_A/D_SEL[3:0] = 0001b	1.76	1.80	1.85	V	
SID197	V <sub>LVI3</sub>	LVI_A/D_SEL[3:0] = 0010b	1.85	1.90	1.95	V	
SID198	V <sub>LVI4</sub>	LVI_A/D_SEL[3:0] = 0011b	1.95	2.00	2.05	V	
SID199	V <sub>LVI5</sub>	LVI_A/D_SEL[3:0] = 0100b	2.05	2.10	2.15	V	
SID200	V <sub>LVI6</sub>	LVI_A/D_SEL[3:0] = 0101b	2.15	2.20	2.26	V	
SID201	V <sub>LVI7</sub>	LVI_A/D_SEL[3:0] = 0110b	2.24	2.30	2.36	V	
SID202	V <sub>LVI8</sub>	LVI_A/D_SEL[3:0] = 0111b	2.34	2.40	2.46	V	
SID203	V <sub>LVI9</sub>	LVI_A/D_SEL[3:0] = 1000b	2.44	2.50	2.56	V	
SID204	V <sub>LVI10</sub>	LVI_A/D_SEL[3:0] = 1001b	2.54	2.60	2.67	V	
SID205	V <sub>LVI11</sub>	LVI_A/D_SEL[3:0] = 1010b	2.63	2.70	2.77	V	
SID206	V <sub>LVI12</sub>	LVI_A/D_SEL[3:0] = 1011b	2.73	2.80	2.87	V	
SID207	V <sub>LVI13</sub>	LVI_A/D_SEL[3:0] = 1100b	2.83	2.90	2.97	V	
SID208	V <sub>LVI14</sub>	LVI_A/D_SEL[3:0] = 1101b	2.93	3.00	3.08	V	
SID209	V <sub>LVI15</sub>	LVI_A/D_SEL[3:0] = 1110b	3.12	3.20	3.28	V	
SID210	V <sub>LVI16</sub>	LVI_A/D_SEL[3:0] = 1111b	4.39	4.50	4.61	V	
SID211	LVI_IDD	Block current	-	_	100	μA	Guaranteed by characterization

# **Table 31. Voltage Monitors AC Specifications**

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID212	T <sub>MONTRIP</sub>	Voltage monitor trip time	_	_	1	μs	Guaranteed by characterization

### SWD Interface

# Table 32. SWD Interface Specifications

Spec ID	Parameter	Description	Min	Тур	Max	Units	Details/Conditions
SID213	F_SWDCLK1	$3.3~V \le V_{DD} \le 5.5~V$	_	-	14	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID214	F_SWDCLK2	$1.71 \text{ V} \le \text{V}_{DD} \le 3.3 \text{ V}$	_	_	7	MHz	SWDCLK ≤ 1/3 CPU clock frequency
SID215	T_SWDI_SETUP	T = 1/f SWDCLK	0.25*T	_	_	ns	Guaranteed by characterization
SID216	T_SWDI_HOLD	T = 1/f SWDCLK	0.25*T	_	_	ns	Guaranteed by characterization
SID217	T_SWDO_VALID	T = 1/f SWDCLK	_	_	0.5*T	ns	Guaranteed by characterization
SID217A	T_SWDO_HOLD	T = 1/f SWDCLK	1	_	_	ns	Guaranteed by characterization

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# **Ordering Information**

The PSoC 4100 part numbers and features are listed in the following table.

Table 39. PSoC 4100 Family Ordering Information

		Features									Package							
							1 60	ıture	<b>.</b>							ıcka	<del></del>	
Family	MPN	Max CPU Speed (MHz)	Flash (KB)	SRAM (KB)	NDB	Op-amp (CTBm)	CapSense	Direct LCD Drive	12-bit SAR ADC	LP Comparators	TCPWM Blocks	SCB Blocks	GPIO	28-SSOP	35-WLCSP	40-QFN	44-TQFP	48-TQFP
	CY8C4124PVI-432	24	16	4	-	1	-	-	806 ksps	2	4	2	24	1				
	CY8C4124PVI-442	24	16	4	-	1	V	√	806 ksps	2	4	2	24	1				
	CY8C4124PVQ-432	24	16	4	-	1	-	-	806 ksps	2	4	2	24	V				
	CY8C4124PVQ-442	24	16	4	-	1	V	V	806 ksps	2	4	2	24	V				
	CY8C4124FNI-443	24	16	4	-	2	V	V	806 ksps	2	4	2	31		V			
	CY8C4124LQI-443	24	16	4	-	2	V	V	806 ksps	2	4	2	34			V		
	CY8C4124AXI-443	24	16	4	-	2	<b>V</b>	1	806 ksps	2	4	2	36				1	
	CY8C4124LQQ-443	24	16	4	-	2	<b>V</b>	1	806 ksps	2	4	2	34			1		
	CY8C4124AXQ-443	24	16	4	-	2	V	1	806 ksps	2	4	2	36				1	
	CY8C4124AZI-443	24	16	4	-	2	V	√	806 ksps	2	4	2	36					$\sqrt{}$
4100	CY8C4125AXI-473	24	32	4	-	2	-	-	806 ksps	2	4	2	36				V	
4	CY8C4125AXQ-473	24	32	4	-	2	-	-	806 ksps	2	4	2	36				<b>V</b>	
	CY8C4125AZI-473	24	32	4	-	2	-	-	806 ksps	2	4	2	36					√
	CY8C4125PVI-482	24	32	4	-	1	V	V	806 ksps	2	4	2	24	V				
	CY8C4125PVQ-482	24	32	4	-	1	V	V	806 ksps	2	4	2	24	V				
	CY8C4125FNI-483(T)	24	32	4	-	2	V	V	806 ksps	2	4	2	31		V			
	CY8C4125LQI-483	24	32	4	-	2	<b>V</b>	√	806 ksps	2	4	2	34			<b>V</b>		
	CY8C4125AXI-483	24	32	4	-	2	<b>V</b>	1	806 ksps	2	4	2	36				1	
	CY8C4125LQQ-483	24	32	4	-	2	V	V	806 ksps	2	4	2	34			<b>V</b>		
	CY8C4125AXQ-483	24	32	4	-	2	V	V	806 ksps	2	4	2	36				<b>V</b>	
	CY8C4125AZI-483	24	32	4	-	2	√	V	806 ksps	2	4	2	36					V

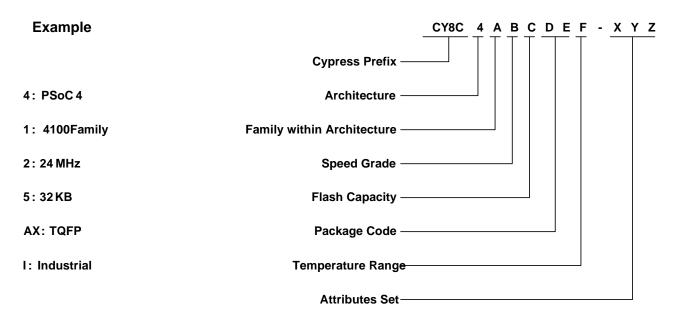
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# **Part Numbering Conventions**

PSoC 4 devices follow the part numbering convention described in the following table. All fields are single-character alphanumeric (0, 1, 2, ..., 9, A,B, ..., Z) unless stated otherwise.

The part numbers are of the form CY8C4ABCDEF-XYZ where the fields are defined as follows.



The Field Values are listed in the following table.

Field	Description	Values	Meaning
CY8C	Cypress Prefix		
4	Architecture	4	PSoC 4
Α	Family within architecture	1	4100 Family
_ ^	army within architecture	2	4200 Family
В	CPU Speed	2	24 MHz
	Cr O Speed	4	48 MHz
С	Flash Capacity	4	16 KB
	Trasti Capacity	5	32 KB
		AX, AZ	TQFP
DE	Package Code	LQ	QFN
"	l ackage code	PV	SSOP
		FN	WLCSP
F	Temperature Range	I	Industrial
	Temperature range	Q	Extended Industrial
XYZ	Attributes Code	000-999	Code of feature set in specific family

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# **Packaging**

**Table 40. Package Characteristics** 

Parameter	Description	Conditions	Min	Тур	Max	Units
T <sub>A</sub>	Operating ambient temperature		-40	25.00	105	°C
T <sub>J</sub>	Operating junction temperature		-40	-	125	°C
$T_{JA}$	Package θ <sub>JA</sub> (28-pin SSOP)		_	66.58	-	°C/Watt
$T_{JA}$	Package θ <sub>JA</sub> (35-ball WLCSP)		_	28.00	_	°C/Watt
$T_{JA}$	Package θ <sub>JA</sub> (40-pin QFN)		_	15.34	_	°C/Watt
$T_{JA}$	Package θ <sub>JA</sub> (44-pin TQFP)		_	57.16	-	°C/Watt
$T_{JA}$	Package θ <sub>JA</sub> (48-pin TQFP)		_	67.30	_	°C/Watt
$T_JC$	Package θ <sub>JC</sub> (28-pin SSOP)		_	26.28	-	°C/Watt
$T_JC$	Package θ <sub>JC</sub> (35-ball WLCSP)		_	00.40	-	°C/Watt
$T_{JC}$	Package θ <sub>JC</sub> (40-pin QFN)		_	2.50	_	°C/Watt
$T_{JC}$	Package θ <sub>JC</sub> (44-pin TQFP)		_	17.47	_	°C/Watt
$T_{JC}$	Package θ <sub>JC</sub> (48-pin TQFP)		_	27.60	_	°C/Watt

Table 41. Solder Reflow Peak Temperature

Package	Maximum Peak Temperature	Maximum Time at Peak Temperature
28-pin SSOP	260 °C	30 seconds
35-ball WLCSP	260 °C	30 seconds
40-pin QFN	260 °C	30 seconds
44-pin TQFP	260 °C	30 seconds
48-pin TQFP	260 °C	30 seconds

Table 42. Package Moisture Sensitivity Level (MSL), IPC/JEDEC J-STD-2

Package	MSL
28-pin SSOP	MSL 3
35-ball WLCSP	MSL 3
40-pin QFN	MSL 3
44-pin TQFP	MSL 3
48-pin TQFP	MSL 3

PSoC 4 CAB Libraries with Schematics Symbols and PCB Footprints are on the Cypress web site at http://www.cypress.com/cad-resources/psoc-4-cad-libraries?source=search&cat=technical\_documents.

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7.50
8.10

DIMENSIONS IN MILLIMETERS MIN.
MAX.

SEATING PLANE

2.00
MAX.

0° MIN.

GAUGE PLANE

2.00
MAX.

0° MIN.

GAUGE PLANE

0° MIN.

GAUGE PLANE

0.65 BSC.

3.65
1.85

GAUGE PLANE

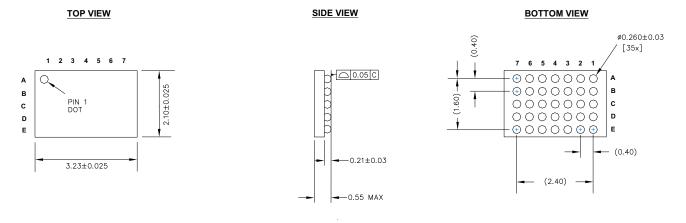
0.025

1.25 REF-

- <u>0.55</u> 0.95

Figure 15. 28-pin (210-mil) SSOP Package Outline

Figure 16. 35-ball WLCSP Package Outline



### NOTES:

- 1. REFERENCE JEDEC PUBLICATION 95, DESIGN GUIDE 4.18
- 2. ALL DIMENSIONS ARE IN MILLIMETERS

001-93741 \*\*

51-85079 \*F



9.00±0.25 SQ -7.00±0.10 SQ DIMENSIONS ARE IN MILLIMETERS 0.20±0.05 0° MIN. R. 0.08 MIN. — 0.20 MAX. STAND-OFF 0.05 MIN. 0.15 MAX. GAUGE PLANE \_ \_ 0.50 TYP. R. 0.08 MIN. 0-7 13 0.20 MIN. 0.60±0.15 12°±1° SEATING PLANE 1.00 REF. 1.60 MAX. DETAILA 1.40±0.05 O.10 0.20 MAX. 51-85135 \*C SEE DETAILA

Figure 19. 48-Pin TQFP Package Outline



Table 43. Acronyms Used in this Document (continued)

Acronym	Description
PC	program counter
PCB	printed circuit board
PGA	programmable gain amplifier
PHUB	peripheral hub
PHY	physical layer
PICU	port interrupt control unit
PLA	programmable logic array
PLD	programmable logic device, see also PAL
PLL	phase-locked loop
PMDD	package material declaration data sheet
POR	power-on reset
PRES	precise power-on reset
PRS	pseudo random sequence
PS	port read data register
PSoC <sup>®</sup>	Programmable System-on-Chip™
PSRR	power supply rejection ratio
PWM	pulse-width modulator
RAM	random-access memory
RISC	reduced-instruction-set computing
RMS	root-mean-square
RTC	real-time clock
RTL	register transfer language
RTR	remote transmission request
RX	receive
SAR	successive approximation register
SC/CT	switched capacitor/continuous time
SCL	I <sup>2</sup> C serial clock
SDA	I <sup>2</sup> C serial data
S/H	sample and hold
SINAD	signal to noise and distortion ratio
SIO	special input/output, GPIO with advanced features. See GPIO.
SOC	start of conversion
SOF	start of frame
SPI	Serial Peripheral Interface, a communications protocol
SR	slew rate
SRAM	static random access memory
SRES	software reset
SWD	serial wire debug, a test protocol

Table 43. Acronyms Used in this Document (continued)

Acronym	Description
SWV	single-wire viewer
TD	transaction descriptor, see also DMA
THD	total harmonic distortion
TIA	transimpedance amplifier
TRM	technical reference manual
TTL	transistor-transistor logic
TX	transmit
UART	Universal Asynchronous Transmitter Receiver, a communications protocol
UDB	universal digital block
USB	Universal Serial Bus
USBIO	USB input/output, PSoC pins used to connect to a USB port
VDAC	voltage DAC, see also DAC, IDAC
WDT	watchdog timer
WOL	write once latch, see also NVL
WRES	watchdog timer reset
XRES	external reset I/O pin
XTAL	crystal

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# **Document Conventions**

# **Units of Measure**

# Table 44. Units of Measure

	nits of Measure
Symbol	Unit of Measure
°C	degrees Celsius
dB	decibel
fF	femto farad
Hz	hertz
KB	1024 bytes
kbps	kilobits per second
Khr	kilohour
kHz	kilohertz
kΩ	kilo ohm
ksps	kilosamples per second
LSB	least significant bit
Mbps	megabits per second
MHz	megahertz
ΜΩ	mega-ohm
Msps	megasamples per second
μΑ	microampere
μF	microfarad
μH	microhenry
μs	microsecond
μV	microvolt
μW	microwatt
mA	milliampere
ms	millisecond
mV	millivolt
nA	nanoampere
ns	nanosecond
nV	nanovolt
Ω	ohm
pF	picofarad
ppm	parts per million
ps	picosecond
s	second
sps	samples per second
sqrtHz	square root of hertz
V	volt
L	ı

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# **Revision History**

Revision	ECN	Orig. of Change	Submission Date	Description of Change
*B	4108562	WKA	08/29/2013	Added clarifying note about the XRES pin in the Reset section.  Added a link reference to the PSoC 4 TRM.  Updated the footnote in Absolute Maximum Ratings.  Updated Sleep Mode IDD specs in DC Specifications.  Updated Comparator DC Specifications  Updated SAR ADC AC Specifications (Guaranteed by Characterization)  Updated LCD Direct Drive DC Specifications (Guaranteed by Characterization)  Updated the number of GPIOs in Ordering Information.
*C	4568937	WKA	11/19/2014	Added 48-pin TQFP pin and package details. Added SID308A spec details. Updated Ordering Information.
*D	4617283	WKA	01/08/2015	Corrected typo in the ordering information table. Updated 28-pin SSOP package diagram.
*E	4643655	WKA	04/29/2015	Added 35 WLCSP pinout and package detail information. Updated CSD specifications.
*F	5287114	WKA	06/09/2016	Corrected typo in the Features section. Added reference to AN90071 in the More Information section. Updated Flash section with details of flash protection modes. Added notes in the Pinouts section. Updated 40-pin QFN and 28-pin SSOP pin diagrams. Added PSoC 4 Power Supply diagram. Updated the Bypass Capacitors column in the Power Supply table. Updated values for SID32, SID34, SID38, SID269, SID270, SID271. Added SID299A. Updated Comparator Specifications. Updated TCPWM Specifications. Updated values for SID149, SID160, SID171. Updated Conditions for SID190. Added BID55. Removed Conditions for SID237. Added reference to PSoC 4 CAB Libraries with Schematics Symbols and PCB Footprints in the Packaging section.
*G	5327384	WKA	06/28/2016	Removed the capacitor connection for Pin 15 in Figure 11.
*H	5704046	GNKK	04/26/2017	Updated the Cypress logo and copyright information.

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